Title (en)

PROCESS AND MANUFACTURING TOOL ARCHITECTURE FOR USE IN THE MANUFACTURE OF ONE OR MORE METALLIZATION LEVELS ON A WORKPIECE

Title (de)

VERFAHREN UND ANORDNUNG EINER HERSTELLUNGSVORRICHTUNG ZUR VERWENDUNG IN DER HERSTELLUNG EINES ODER MEHRERER METALLISIERUNGSNIVEAUS AUF EINEM WERKSTÜCK

Title (fr)

OUTIL SERVANT A FABRIQUER UN OU PLUSIEURS NIVEAUX DE METALLISATION SUR UN COMPOSANT A SEMICONDUCTEUR ET PROCEDE CORRESPONDANT

Publication

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Application

EP 99922934 A 19990512

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Abstract (en)

[origin: WO9959190A2] A semiconductor manufacturing tool configuration and corresponding process for applying one or more levels of interconnect metallization to a generally planar dielectric surface of a semiconductor workpiece with a minimal number of workpiece transfer operations between the tool sets is disclosed.

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H01L 21/00

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